

	Type	Hits	Search Text
1	BRS	13	(thermal adj interface adj material) and binder and filler
2	BRS	7	(thermal adj interface adj material) and binder and solder\$3
3	BRS	1	(thermal adj interface adj material) and (solder\$3 adj alloy)
4	BRS	21	(thermal adj interface adj material) and (tin or indium)
5	BRS	1	(binder same (tin or indium)) and (thermal adj interface)
6	BRS	14	((binder same (tin or indium) same filler)) and chip
7	BRS	1	((binder same (tin or indium) same filler)) and (thermal adj interface)
8	BRS	0	(binder same (fusible adj metal)) and (thermal adj interface)
9	BRS	253	(binder same (tin or indium) same filler)
10	BRS	124	(binder same (tin or indium) same coat\$3 same filler)
11	BRS	2	((binder same (tin or indium) same coat\$3 same filler) ) and (heat adj sink)
12	BRS	6	((binder same (tin or indium) same coat\$3 same filler) ) and (thermal with conductive)
13	BRS	4	((binder same (tin or indium) same filler)) and (heat adj sink)
14	BRS	1	((binder same (tin or indium) same filler)) and (thermal adj interface)

	DBs	Time Stamp	Comments	Error Definition
1	USPAT; JPO; DERWENT	2003/01/16 15:30		
2	USPAT; JPO; DERWENT	2003/01/16 15:34		
3	USPAT; JPO; DERWENT	2003/01/16 15:37		
4	USPAT; JPO; DERWENT	2003/01/16 16:27		
5	USPAT; JPO; DERWENT	2003/01/16 16:29		
6	USPAT; JPO; DERWENT	2003/01/16 16:43		
7	USPAT; JPO; DERWENT	2003/01/16 16:43		
8	USPAT; JPO; DERWENT	2003/01/16 16:44		
9	USPAT; JPO; DERWENT	2003/01/16 17:29		
10	USPAT; JPO; DERWENT	2003/01/16 17:30		
11	USPAT; JPO; DERWENT	2003/01/16 17:31		
12	USPAT; JPO; DERWENT	2003/01/16 17:33		
13	USPAT; JPO; DERWENT	2003/01/16 17:34		
14	USPAT; JPO; DERWENT	2003/01/16 17:34		